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Omichi

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(54) **SEMICONDUCTOR MODULE**

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H05K 1/18; H05K 1/181; H05K 1/182;
H05K 1/026

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See application file for complete search history.

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(**) Term: **15 Years**

(21) Appl. No.: **29/705,573**

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(30) **Foreign Application Priority Data**

(Continued)

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(51) **LOC (12) Cl.** **13-03**

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(52) **U.S. Cl.**
USPC **D13/182**

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361/679.01, 713, 728, 736, 760, 761, 772,
361/775, 783, 820; 174/250, 253;
438/15, 25, 26, 51, 55, 63, 64, 106
CPC . H01L 21/00; H01L 2224/42; H01L 2224/43;
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G02B 6/428; G02B 6/4281; H05K 1/14;

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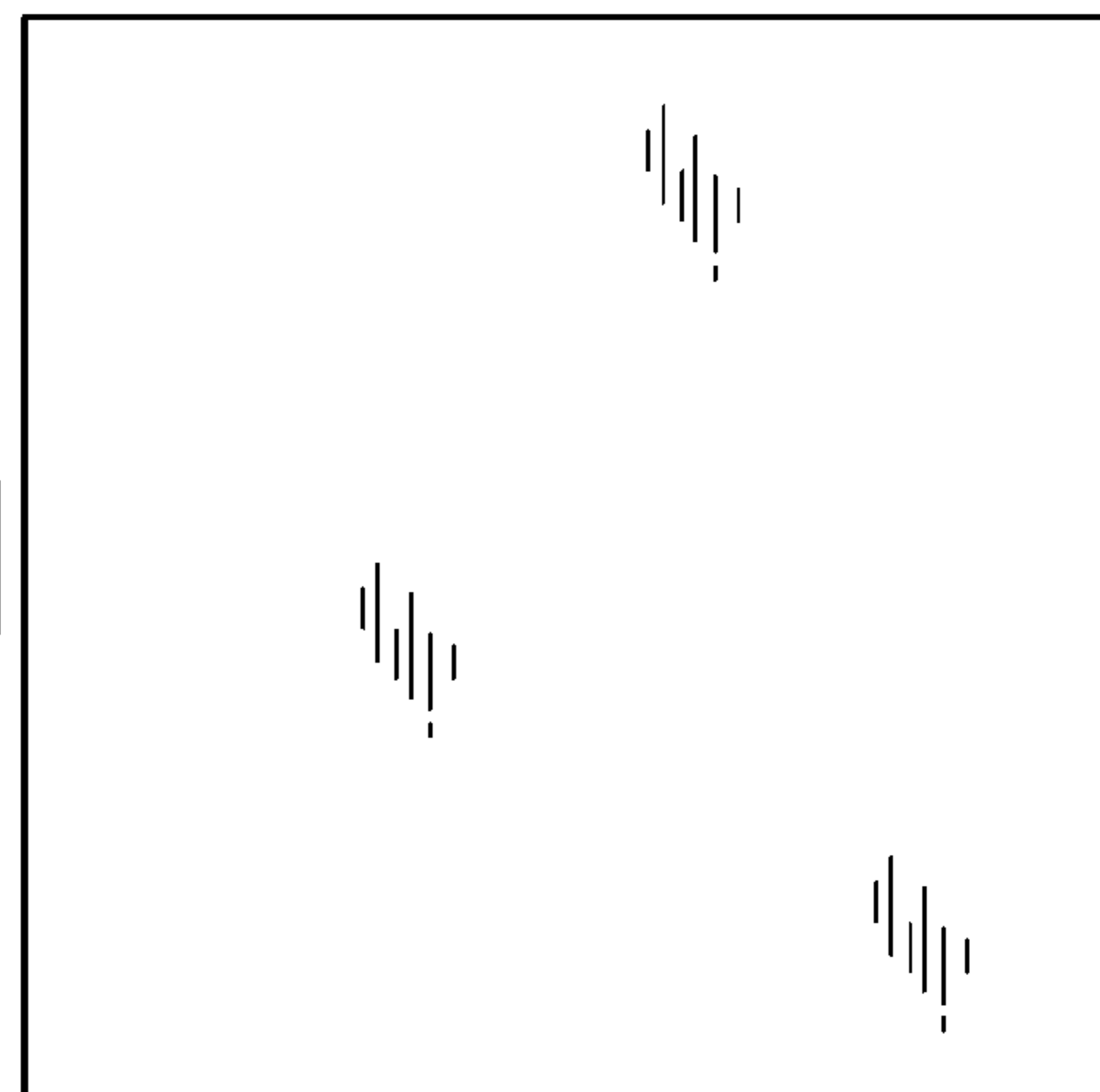
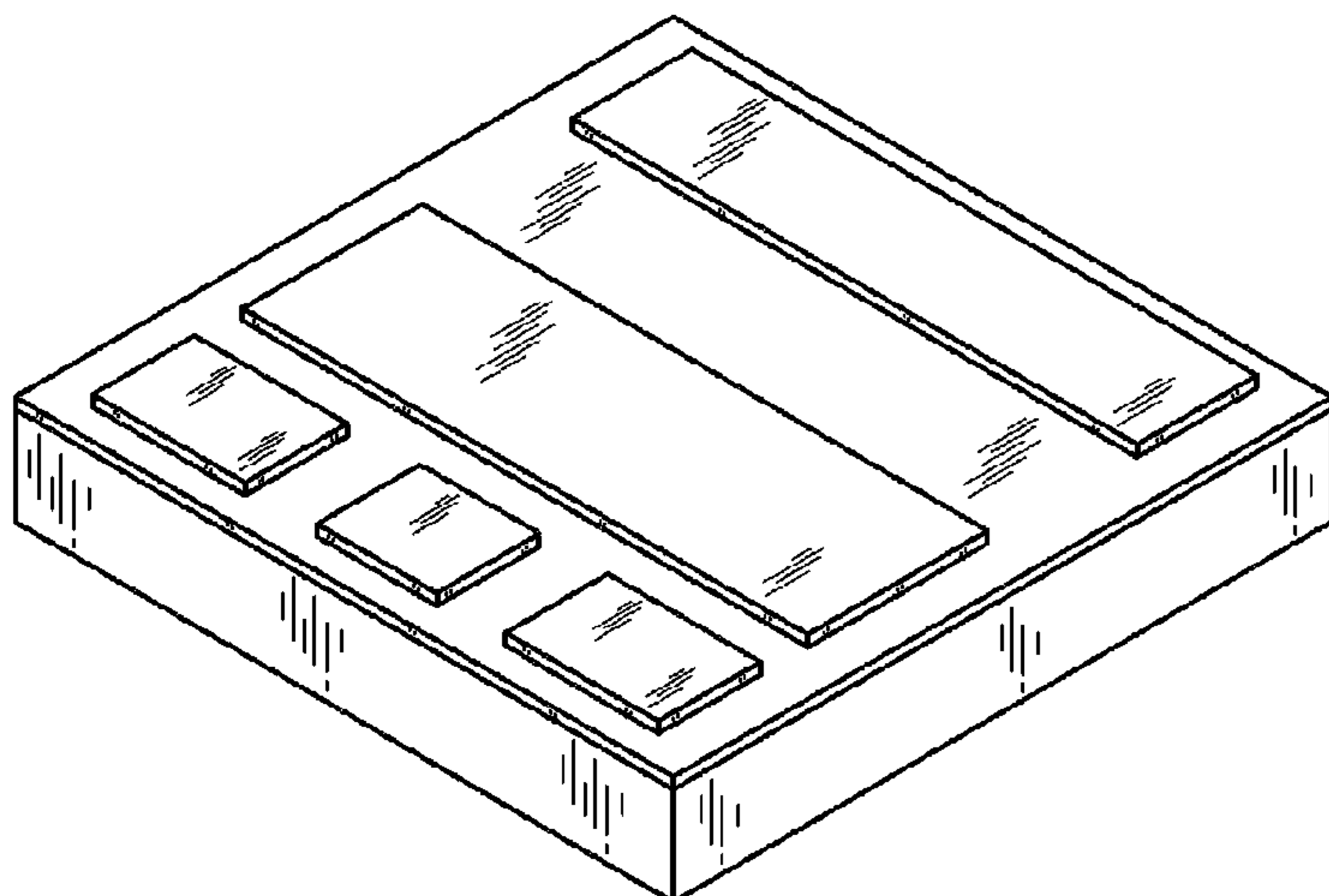
(57) **CLAIM**

The ornamental design for a semiconductor module, as shown and described.

DESCRIPTION

FIG. 1 is a rear perspective view of a semiconductor module showing my new design;
FIG. 2 is a front view thereof;
FIG. 3 is a top view thereof, the bottom view is a mirror image of the top view;
FIG. 4 is a left side view thereof;
FIG. 5 is a rear view thereof; and,
FIG. 6 is a right side view thereof.

1 Claim, 3 Drawing Sheets



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Fig. 1

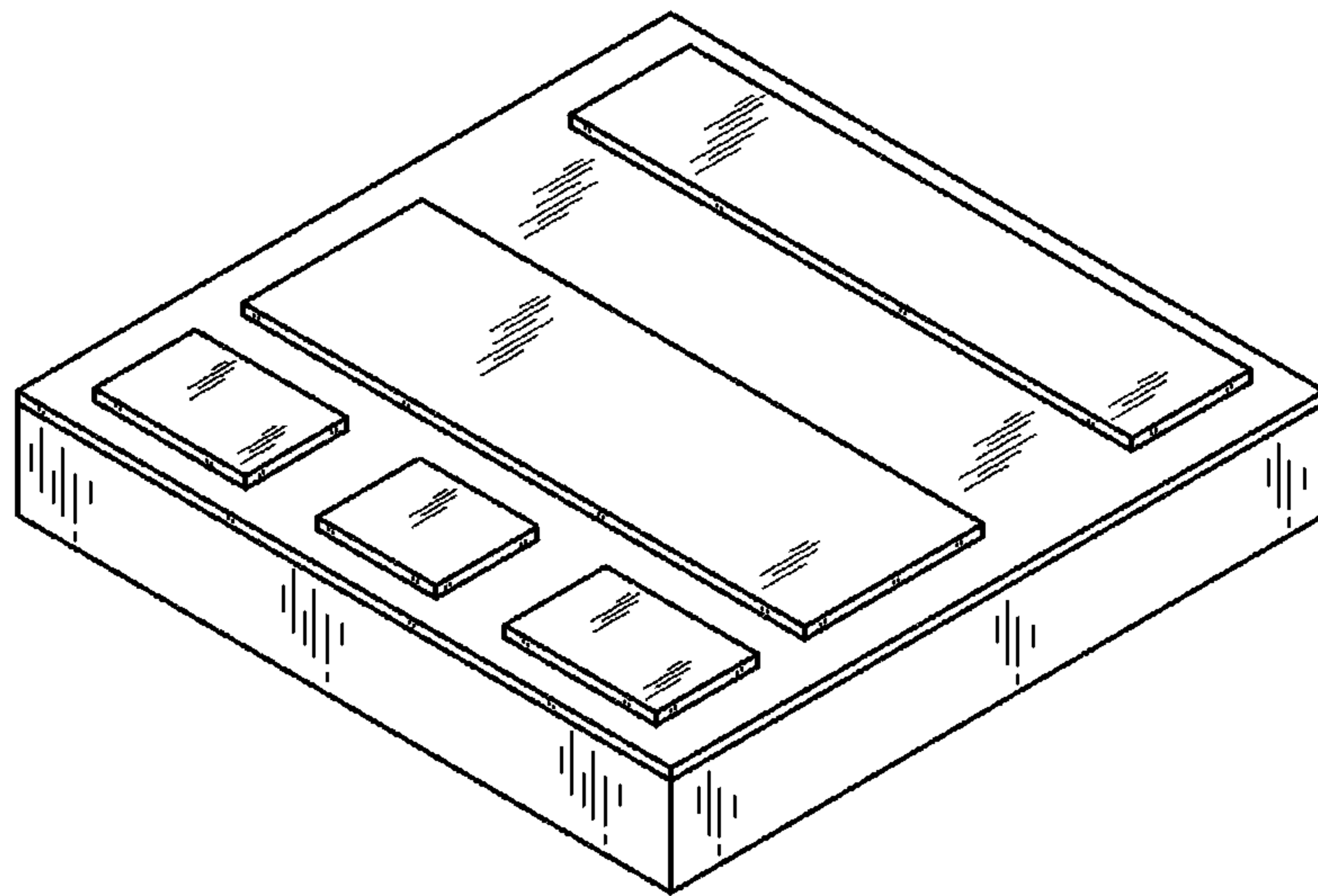


Fig.2

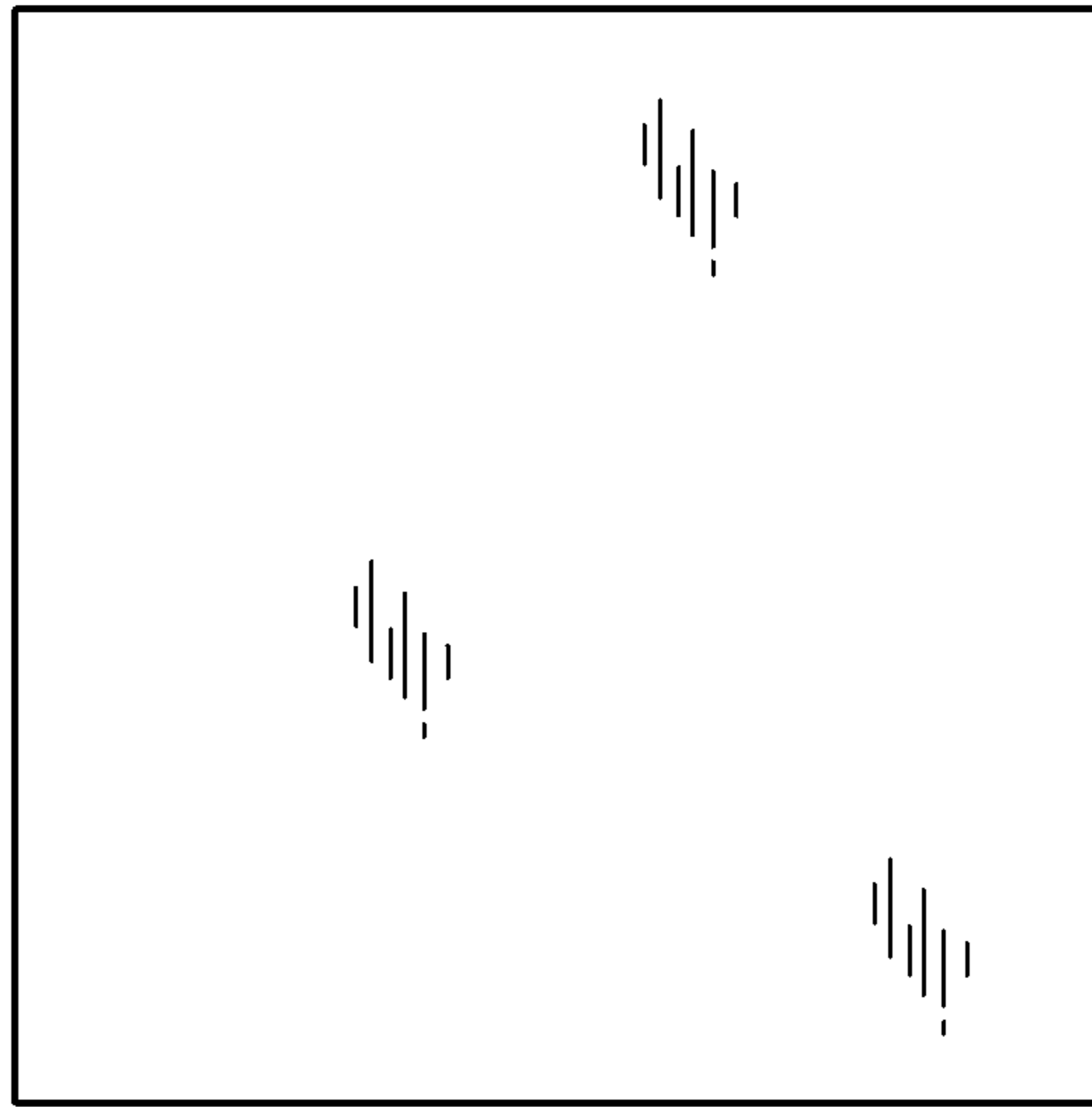


Fig.3

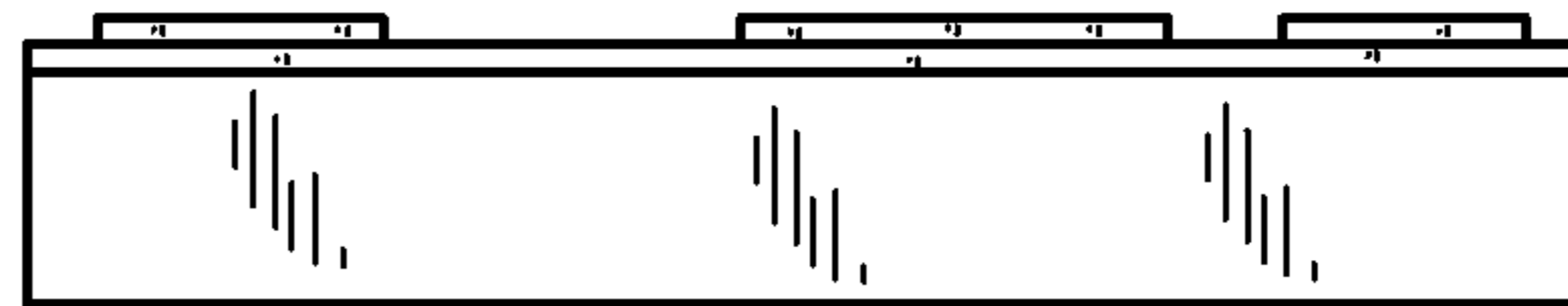


Fig.4

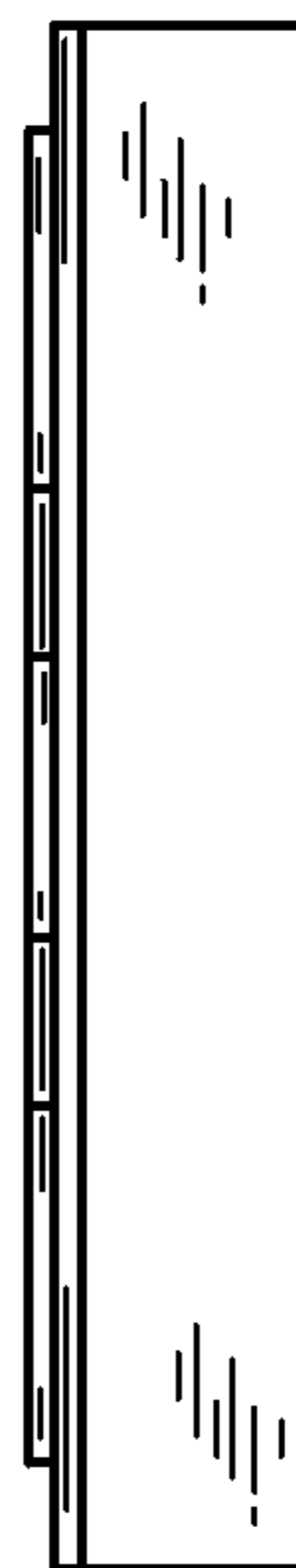


Fig.5

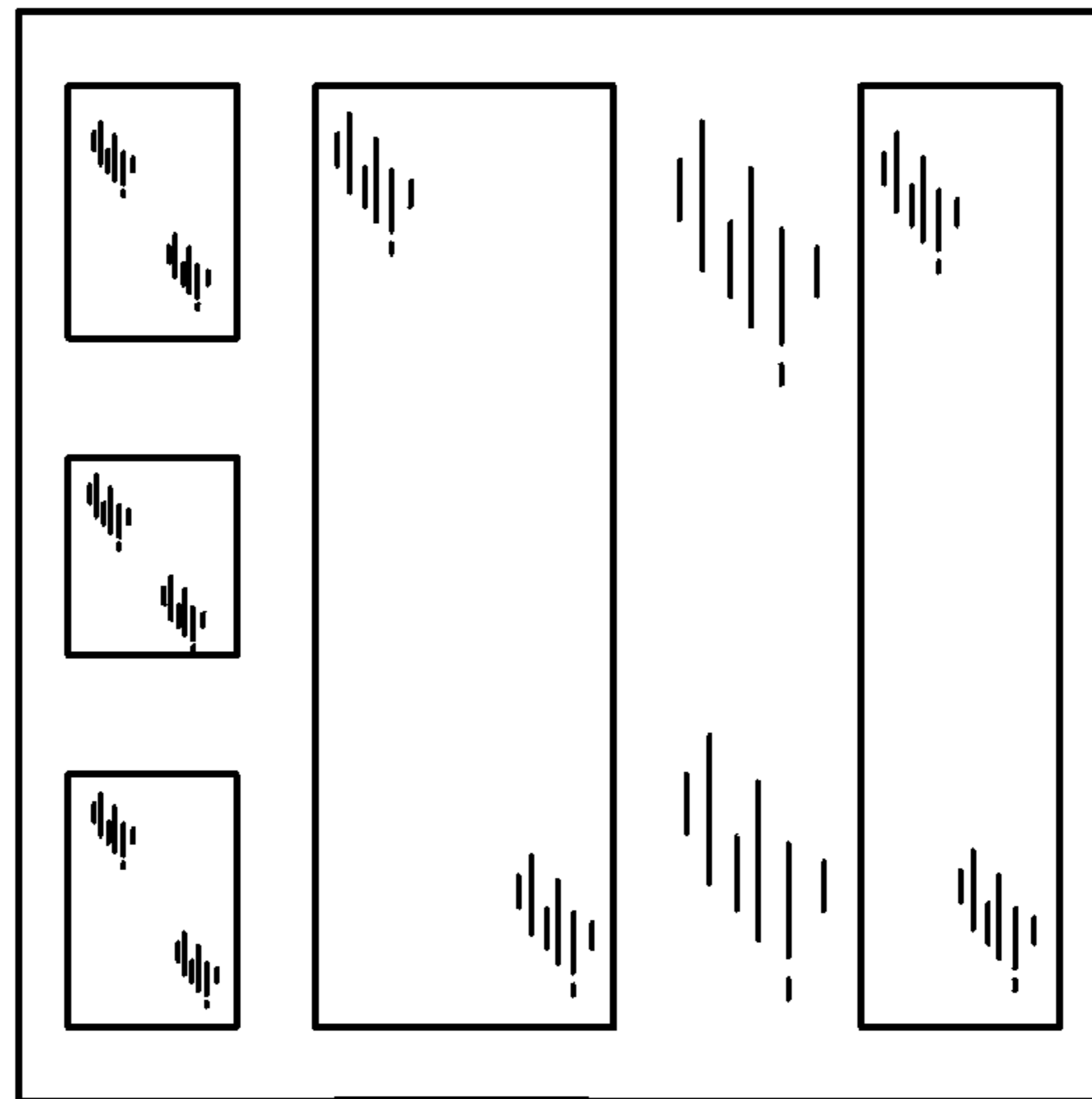


Fig.6

